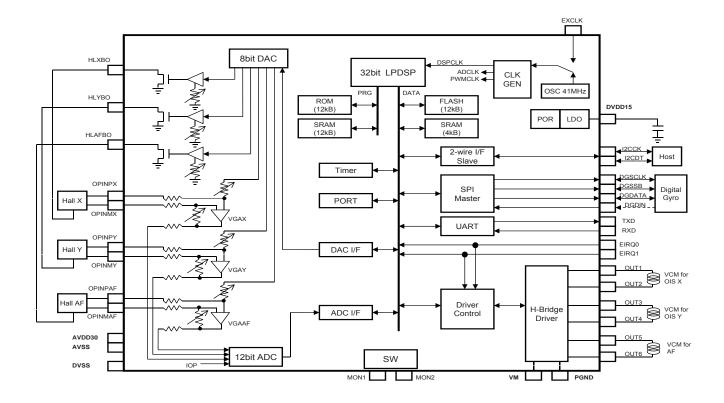
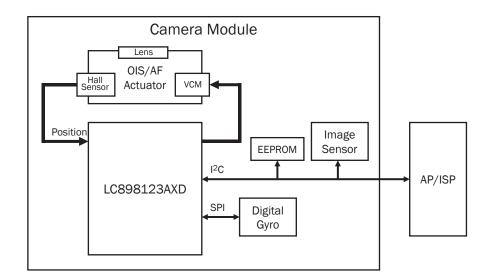
Block Diagram



Application Diagram

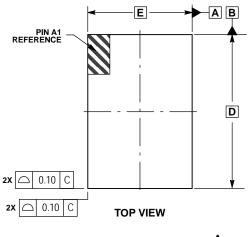


Package Dimensions

unit: mm

WLCSP35, 3.39x2.3

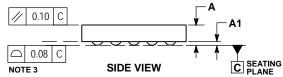
CASE 567JG **ISSUE O**

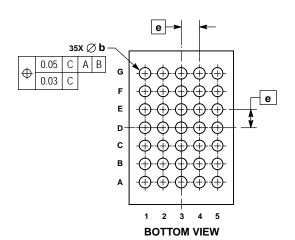




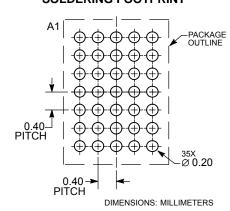
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

| | MILLIN | MILLIMETERS | | | | | |
|-----|----------|-------------|--|--|--|--|--|
| DIM | MIN | MAX | | | | | |
| Α | | 0.45 | | | | | |
| A1 | 0.03 | 0.13 | | | | | |
| b | 0.15 | 0.25 | | | | | |
| D | 3.39 | BSC | | | | | |
| Е | 2.30 BSC | | | | | | |
| е | 0.40 | BSC | | | | | |





RECOMMENDED SOLDERING FOOTPRINT*

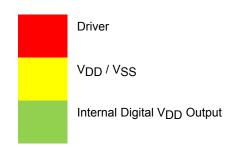


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Pin Assignment

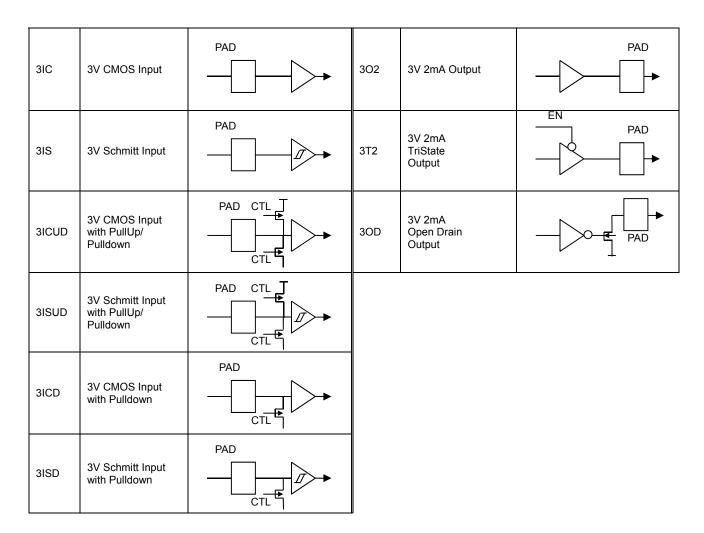
Bottom View

| 5 | OUT5 | OUT3 | OUT4 | PGND | OUT2 | OUT1 | WPB |
|---|-------------|--------|-------------|--------|--------|--------|-------|
| 4 | OUT6 | DGDATA | DGSSB | VM | I2CDT | I2CCK | TXD |
| 3 | HLAFBO | DGSCLK | DVSS | NC | EXCLK | DGDIN | EIRQ1 |
| 2 | HLYBO | HLXBO | OPINM AF | OPINMX | OPINMY | EIRQ0 | MON2 |
| 1 | OPINP AF | OPINPX | OPINPY | AVSS | AVDD30 | DVDD15 | MON1 |
| ' | G | F | E | D | С | В | A |



Pin Description

| | I/O Pin Specification | | | | |
|---|-----------------------|-------|--|-------|---------------------|
| I | Input | 3IC | 3V CMOS Input | 3IA | 3V Analog Input |
| 0 | Output | 3IS | 3V CMOS Schmitt Input | 3OA | 3V Analog Output |
| В | Bidirection | 3ICUD | 3V CMOS Input with PullUp/PullDown | | |
| Р | Power | 3ISUD | 3V CMOS Schmitt Input with PullUp/PullDown | | |
| | | 3ICD | 3V CMOS Input with PullDown | | |
| | | 3ISD | 3V CMOS Schmitt Input with PullDown | | |
| | | | | | |
| | | 302 | 3V 2mA Output | | |
| | | 3T2 | 3V 2mA TriState Output | Z/U/D | HiZ/PullUp/PullDown |
| | | 3OD | 3V 2mA Open Drain Output | H/L | HIGH/LOW |



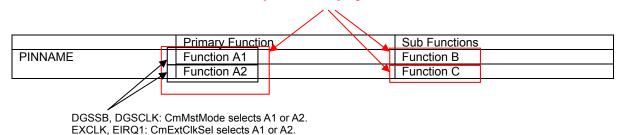
| | Pin | I/O | I/O S | рес | Primary Function | Sub Functions | Init |
|----|--------|-----|-------|------------|---|---|------|
| A1 | MON1 | В | 3ICUD | 3T2 3OA | (Debugger Data Output) | I2C Data I/O for DAC Monitor Servo Monitor Analog Out Internal Signal Monitor | L |
| A2 | MON2 | В | 3ICUD | 3T2 3OA | (Debugger Data Input) | I2C Data I/O for DAC Monitor Servo Monitor Analog Out Internal Signal Monitor | z |
| А3 | EIRQ1 | В | 3ISUD | 3T2 3OA | External IRQ1 External Clock Input | I2C Data I/O for DAC Monitor UART Data Output(TXD) Internal Signal Monitor Servo Monitor Analog Input | z |
| A4 | TXD | В | 3ICUD | 3T2 | UART Data Output | I2C Data I/O for DAC Monitor I2C Clock for I2C Slave Internal Signal Monitor | Z |
| A5 | WPB | I | 3ICD | | Write Protect Input | | - |
| B1 | DVDD15 | Р | | | Internal LDO Power Output | | - |
| B2 | EIRQ0 | В | 3ICD | 3OD | External IRQ0 | I2C Data I/O for DAC Monitor UART Data Input(RXD) Internal Signal Monitor | Z |
| В3 | DGDIN | В | 3ICUD | 3T2 | Digital Gyro Data Input (4 Wired) | I2C Data I/O for DAC Monitor Internal Signal Monitor | U |
| B4 | I2CCK | В | 3IS | 3OD | I2C Clock | | Z |
| B5 | OUT1 | 0 | | 3OA | OIS Driver Output (H-Bridge or Linear) | | - |
| C1 | AVDD30 | Р | | | Analog Power (2.6 to 3.6V) | | - |
| C2 | OPINMY | I | 3IA | | OIS Hall Y Op-amp Input Minus | | - |
| СЗ | EXCLK | В | 3ISD | 3OD | External Clock Input External IRQ1 | I2C Data I/O for DAC Monitor Internal Signal Monitor | z |
| C4 | I2CDT | В | 3IS | 3OD | I2C Data | | Z |
| C5 | OUT2 | 0 | | 3OA | OIS Driver Output (H-Bridge or Linear) | | - |
| D1 | AVSS | Р | | | Analog GND | | - |
| D2 | OPINMX | I | 3IA | | OIS Hall X Op-amp Input Minus | | - |
| D3 | NC | - | | | No Connection | | - |
| D4 | VM | Р | | | Driver Power (2.6V to 3.6V) | | - |
| D5 | PGND | Р | | | Driver GND | | - |

| | Pin | I/O | I/O S | рес | Primary Function | Sub Functions | Init |
|-----|-------------|-----|-------|-----|---|-------------------------------------|------|
| E1 | OPINPY | ı | 3IA | | OIS Hall Y Op-amp Input Plus | | - |
| E2 | OPINMA F | I | 3IA | | AF Hall Op-amp Input Minus | | - |
| E3 | DVSS | Р | | | Logic GND | | - |
| E4 | DGSSB | В | 3ICUD | 3T2 | Digital Gyro I/F Chip Select Input | Digital Gyro I/F Chip Select Output | U |
| | БСООВ | D | 31000 | 012 | Digital Gyro I/F Chip Select Output | Internal Signal Monitor | Ŭ |
| E5 | OUT4 | 0 | | 30A | OIS Driver Output (H-Bridge or Linear) | | - |
| F1 | OPINPX | ı | 3IA | | OIS Hall X Op-amp Input Plus | | - |
| F2 | HLXBO | 0 | | 30A | OIS Hall X Bias Output | | - |
| F3 | DGSCLK | В | 3ICUD | 3T2 | Digital Gyro I/F Clock Input | Digital Gyro Clock Output | U |
| гэ | DGSCLK | Ь | 31000 | 312 | Digital Gyro I/F Clock Output | I2C Clock for I2C Slave | U |
| F4 | DGDATA | В | 3ICUD | 3T2 | Digital Gyro Data I/F Output | Digital Gyro I/F Data I/O(3 Wired) | U |
| 1 7 | DODATA | Ь | 31000 | 312 | (4 Wired) | I2C Data for I2C Slave | U |
| F5 | OUT3 | 0 | | 3OA | OIS Driver Output (H-Bridge or Linear) | | - |
| G1 | OPINPAF | I | 3IA | | AF Hall Op-amp Input Plus | | - |
| G2 | HLYBO | 0 | | 3OA | OIS Hall Y Bias Output | | - |
| G3 | HLAFBO | 0 | | 30A | AF Hall Bias Output | | - |
| G4 | OUT6 | 0 | | 3OA | AF Driver Output (H-Bridge, Linear) | | - |
| G5 | OUT5 | 0 | | 3OA | AF Driver Output (H-Bridge, Linear) | | - |

[How to select the function]

The initial function right after reset is set to be "Function A1" in the below table. You can change the function by CmIOPN, CmMstMode, CmExtClkSel.

One of Function A,B,C... can be selected by CmIOPN [N=0,1,2,...10] register.



Electrical Characteristics

Logic

Absolute Maximum Rating at V_{SS}=0V

| Parameter | Symbol | Conditions | Ratings | Unit |
|-----------------------|--|------------|--------------------------------|------|
| Power supply voltage | V _{AD} 30 max | Ta ≤ 25°C | -0.3 to 4.6 | V |
| Innut/Output valtage | V _{AI} 30, V _{AO} 30 | Ta ≤ 25°C | -0.3 to V _{AD} 30+0.3 | V |
| Input/Output voltage | V _{DI} 30, V _{DO} 30 | Ta ≤ 25°C | -0.3 to V _{AD} 30+0.3 | V |
| Storage temperature | Tstg | | –55 to 125 | °C |
| Operating temperature | Topr | | −30 to 85 | °C |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Allowable Operating Ratings at Ta=-30 to 85°C, VSS=0V

3.0V Power Supply (AVDD30)

| Parameter | Symbol | Min | Тур | Max | Unit |
|----------------------|--------------------|-----|-----|--------------------|------|
| Power supply voltage | V _{AD} 30 | 2.6 | 2.8 | 3.6 | V |
| Input voltage range | VIN | 0 | - | V _{AD} 30 | V |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

D.C. Characteristics at Input/Output V_{SS}= 0V, AV_{DD}30=2.6 to 3.6V, Ta =–30 to 85°C

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit | Applicable I/O |
|---------------------------|--------|------------|-----------------------------|-----|---------------------|------|-----------------------------|
| High-level input voltage | VIH | CMOS | 1.48 | | | V | 3IS, 3ISUD, |
| Low-level input voltage | VIL | schmitt | | | 0.37 | V | 3ISD |
| High-level input voltage | VIH | CMOS | 1.40 | | | | 3IC, 3ICUD, |
| Low-level input voltage | VIL | supported | | | 0.51 | V | 3ICD |
| High-level output voltage | VOH | IOH=-2mA | AV _{DD} 30 -0.4 | | | ٧ | 3O2, 3T2 |
| Low-level output voltage | VOL | IOL= 2mA | | | 0.4 | ٧ | 302, 312 |
| Low-level output voltage | VOL | IOL= 2mA | | | 0.2 | > | 3OD |
| Analog input voltage | VAI | | AVSS | | AV _{DD} 30 | V | 3IA |
| PullUp resistor | Rup | | 50 | _ | 200 | kΩ | 3ICUD, 3ISUD |
| PullDown resistor | Rdn | | 50 | | 220 | kΩ | 3ICUD, 3ISUD, 3ISD, 3ICD |

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Non-volatile Memory Characteristics

| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|----------------|--------|-----------|-----|-----|------|--------|
| Endurance | EN | | | | 1000 | Cycles |
| Data retention | RT | | 10 | | | Years |

Driver

Absolute Maximum Ratings

| Parameter | Symbol | Condition | Ratings | Symbol |
|---------------------------|--------|---|------------|----------|
| Power supply voltage | VM max | | 4.6 | V |
| Output peak current | lopeak | OUT1 to 4 T ≤ 10ms, ON-duty ≤ 20% OUT5, OUT6 t ≤ 10ms, ON-duty ≤ 20% | 300 200 | mA mA |
| Output continuous current | lomov | OUT1 to 4 | 220 | mA |
| | lomax | OUT5, OUT6 | 150 | mA |

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

Allowable Operating Range

| Parameter | Symbol | Condition | Ratings | Symbol |
|----------------------|--------|-----------|------------|--------|
| Ambient temperature | Topg | | −30 to +85 | °C |
| Power supply voltage | VM | | 2.6 to 3.6 | V |

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

H-Bridge Driver Output Characteristics at Ta=25°C, AV_{DD}30=VM=3.0V

| Parameter | Symbol | Condition | Ratings (Ω) | Symbol |
|----------------------|--------|----------------|-------------|--------|
| Output ON resistance | Ronu | lo=220mA (Pch) | 1.1 | Ω |
| OUT1 to OUT4 | Rond | lo=220mA (Nch) | 1.3(*) | Ω |
| Output ON resistance | Ronu | lo=150mA (Pch) | 1.5 | Ω |
| OUT5, OUT6 | Rond | lo=150mA (Nch) | 1.4(*) | Ω |

^(*) include Constant current detect resistance

Constant Current Driver Output at Ta=25°C, AV_{DD}30=VM=2.8V

| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|---------------------------------|-------------------|---|-------|-------|-------|------|
| Output Current OUT1 to OUT4 | | OIS_DA[10:0]=7FFh OIS_DB[10:0]=7FFh | 185.5 | 195.0 | 205.0 | mA |
| Output Current OUT5, OUT6 | l _{full} | OP-AF(unidirection) AF_D[9:0]=3FFh | | 125.0 | | mA |
| | | OP-AF(bidirection) CL-AF AF_D[9:0]=3FFh | | 120.0 | | mA |
| Compliance Voltage OUT1 to OUT4 | | | 0.4 | | | ٧ |
| Compliance Voltage OUT5,OUT6 | Vcomp | OP-AF(unidirection) | 0.4 | | | V |
| | | OP-AF(bidirection) CL-AF | 0.5 | | | V |

Total output current is less than 500mA.

OP-AF (unidirection)

VCM registance (Rvcm) = $(VM - Vcomp)/lo [\Omega]$

OP-AF (bidirection) / CL-AF / OIS

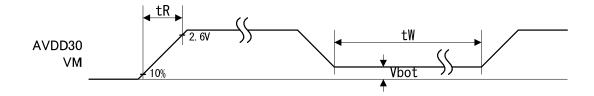
VCM registance (Rvcm) = $(VM - (Ronu \times Io + Vcomp))/Io[\Omega]$

Output ON resistance (Ron) = VM / Io – Rvcm $[\Omega]$

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

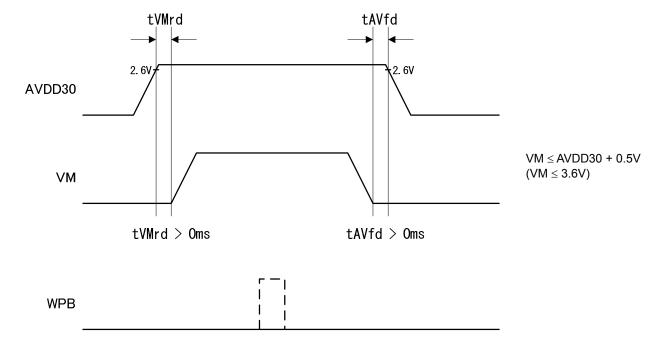
AC Characteristics

Power Sequence



| Item | Symbol | Min | Тур | Max | Units |
|----------------|--------|-----|-----|-----|-------|
| Rise time | tR | | | 5 | ms |
| Wait time | tW | 100 | | | ms |
| Bottom Voltage | Vbot | | | 0.2 | V |

Injection order between AVDD30 and VM is below.



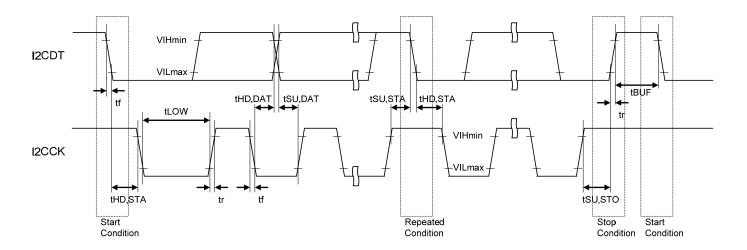
WPB must be open or pull down normally. When Erase or Program is made to Flash, WPB have to be High. Before power off of AVDD, Flash I/F must reset and OSC must set to standby. I2CDT,I2CCK,EXCLK and EIRQ0 tolerate 3V input at the time of power off.

The data in the flash memory may be rewrited if you do not keep specifications.

And it is forbidden to power off during flash access. The data in the flash memory may be rewrited.

2-wire serial Interface Timing

The communication protocol is compatible with I²C (Fast mode Plus). This circuit has clock stretch function.



I²C interface timing definition

| Item | Symbol | Pin name | Min | Тур | Max | Units |
|---|---------|----------------|--------|-----|------|-------|
| SCL clock frequency | Fscl | I2CCK | | | 1000 | kHz |
| START condition hold time | tHD,STA | I2CCK I2CDT | 0.26 | | | μS |
| SCL clock Low period | tLOW | I2CCK | 0.5 | | | μS |
| SCL clock High period | tHIGH | I2CCK | 0.26 | | | μS |
| Setup time for repetition START condition | tSU,STA | I2CCK I2CDT | 0.26 | | | μS |
| Data hold time | tHD,DAT | I2CCK I2CDT | 0 (*1) | | 0.9 | μS |
| Data setup time | tSU,DAT | I2CCK I2CDT | 50 | | | ns |
| SDA, SCL rising time | tr | I2CCK I2CDT | | | 120 | ns |
| SDA, SCL falling time | tf | I2CCK I2CDT | | | 120 | ns |
| STOP condition setup time | tSU,STO | I2CCK I2CDT | 0.26 | | | μS |
| Bus free time between STOP and START | tBUF | I2CCK I2CDT | 0.5 | | | μS |

^(*1) Although the I²C specification defines a condition that 300 ns of hold time is required internally, LC898123AXD is designed for a condition with typ. 100 ns of hold time. If SDA signal is unstable around falling point of SCL signal, please implement an appropriate treatment on board, such as inserting a resistor.

ORDERING INFORMATION

| Device | Package | Shipping (Qty / Packing) |
|----------------|---|--------------------------|
| LC898123AXD-VH | WLCSP35, 3.39x2.3 (Pb-Free / Halogen Free) | 4000 / Tape & Reel |

[†] For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D. http://www.onsemi.com/pub_link/Collateral/BRD8011-D.PDF

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